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# ISL9K460P3 8 A, 600 V, STEALTH™ II Diode

## **Features**

- Stealth Recovery  $t_{rr}$  = 17 ns (@  $I_F$  = 4 A)
- Max Forward Voltage, V<sub>F</sub> = 2.4 V (@ T<sub>C</sub> = 25°C)
- 600 V Reverse Voltage and High Reliability
- · Avalanche Energy Rated
- · RoHS Compliant

## **Applications**

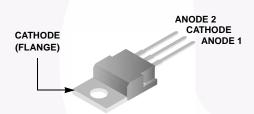
- SMPS FWD
- · Hard Switched PFC Boost Diode
- UPS Free Wheeling Diode
- Motor Drive FWD
- Snubber Diode

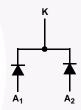
## Description

The ISL9K460P3 is a STEALTH $^{\rm TM}$  dual diode optimized for low loss performance in high frequency hard switched applications. The STEALTH $^{\rm TM}$  family exhibits low reverse recovery current ( $I_{\rm rr}$ ) and exceptionally soft recovery under typical operating conditions. This device is intended for use as a free wheeling or boost diode in power supplies and other power switching applications. The low  $I_{\rm rr}$  and short ta phase reduce loss in switching transistors. The soft recovery minimizes ringing, expanding the range of conditions under which the diode may be operated without the use of additional snubber circuitry. Consider using the STEALTH $^{\rm TM}$  diode with an SMPS IGBT to provide the most efficient and highest power density design at lower cost.

# Package Symbol

## **JEDEC TO-220AB**



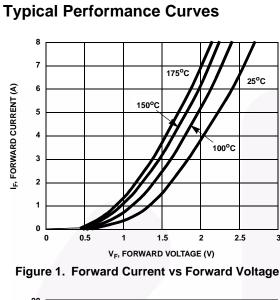


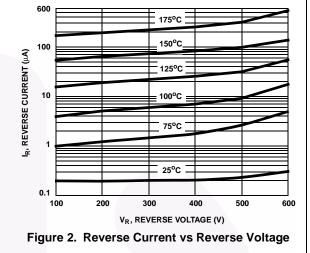
# **Device Maximum Ratings (per leg)** T<sub>C</sub>= 25°C unless otherwise noted

Symbol	Parameter	Rating	Unit	
$V_{RRM}$	Peak Repetitive Reverse Voltage	600		
$V_{RWM}$	Working Peak Reverse Voltage	600	V	
V <sub>R</sub>	DC Blocking Voltage	600	V	
I <sub>F(AV)</sub>	Average Rectified Forward Current (T <sub>C</sub> = 155°C)	4	Α	
	Total Device Current (Both Legs)	8	Α	
I <sub>FRM</sub>	Repetitive Peak Surge Current (20kHz Square Wave)	8	Α	
I <sub>FSM</sub>	Nonrepetitive Peak Surge Current (Halfwave 1 Phase 60Hz)	50	Α	
P <sub>D</sub>	Power Dissipation	58	W	
E <sub>AVL</sub>	Avalanche Energy (0.5A, 80mH)	10	mJ	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to 175	°C	
TL	Maximum Temperature for Soldering	300	°C	
$T_{PKG}^{-}$	Leads at 0.063in (1.6mm) from Case for 10s	260	°C	
	Package Body for 10s, See Techbrief TB334			

CAUTION: Stresses above those listed in "Device Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

art Num	ber	Top Mark	Package	Packing Method	Reel Size	Tape	Width	Qı	antity	
ISL9K460P3		SL9K460P3	TO-220	Tube	N/A	N/A			50	
Electric	al Cl	naracteris	stics (per leg	T <sub>C</sub> = 25°C unless otl	nerwise noted					
Symbol Parameter			Test Conditions		Min	Тур	Max	Unit		
off State	Char	acteristics				J.			L	
I <sub>R</sub>	Instantaneous Reverse Current		V <sub>R</sub> = 600 V	T <sub>C</sub> = 25°C	-	-	100	μА		
				K	T <sub>C</sub> = 125°C	-	-	1.0	mA	
n State	Char	acteristics			-	•			•	
V <sub>F</sub>			rd Voltage	I <sub>F</sub> = 4 A	T <sub>C</sub> = 25°C	_	2.0	2.4	V	
* F	motari	Instantaneous Forward Voltage		1F - 4 \(\chi\)	$T_{\rm C} = 125^{\circ}{\rm C}$	-	1.6	2.0	V	
	01	4			C 1	<b>I</b>			Į.	
		acteristics								
СЈ	Junctio	on Capacitance	)	$V_R = 10 \text{ V}, I_F = 0 \text{ A}$		-	19	-	pF	
witchin	g Cha	racteristics	5							
t <sub>rr</sub>	t <sub>rr</sub> Reverse Recovery Time		$I_F = 1 \text{ A}, di_F/dt = 100$	$0 \text{ A/}\mu\text{s}, \text{ V}_{\text{R}} = 30 \text{ V}$	-	17	20	ns		
				$I_F = 4 \text{ A}, di_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	19	22	ns	
t <sub>rr</sub>	Reverse Recovery Time		$I_F = 4 \text{ A},$ $di_F/dt = 200 \text{ A/}\mu\text{s}, V_R = 390 \text{ V},$ $T_C = 25^{\circ}\text{C}$		-	17	-	ns		
I <sub>rr</sub>	Reverse Recovery Current				-	2.6	-	Α		
Q <sub>rr</sub>	Reverse Recovery Charge				-	22	-	nC		
t <sub>rr</sub>	Reverse Recovery Charge Reverse Recovery Time Softness Factor (t <sub>-</sub> /t <sub>-</sub> )		$I_F = 4 \text{ A},$ $di_F/dt = 200 \text{ A/}\mu\text{s},$ $V_R = 390 \text{ V},$ $T_C = 125^{\circ}\text{C}$		-	77	-	ns		
S	Reverse Recovery Time Reverse Recovery Current Reverse Recovery Charge Reverse Recovery Time				-	4.2	-			
Irr	Reverse Recovery Charge Reverse Recovery Time Softness Factor (t <sub>b</sub> /t <sub>a</sub> ) Reverse Recovery Current				-	2.8	-	Α		
Q <sub>rr</sub>	Revers	se Recovery C	harge	1 <sub>C</sub> = 125 C		-	100	-	nC	
t <sub>rr</sub>	Revers	se Recovery Ti	me	I <sub>F</sub> = 4 A,			54	-	ns	
S	Softne	ss Factor (t <sub>b</sub> /t <sub>a</sub>	)	$di_F/dt = 400 \text{ A/}\mu\text{s},$		-	3.5	-		
Irr	Reverse Recovery Time  Softness Factor (t <sub>b</sub> /t <sub>a</sub> )  Reverse Recovery Current  Reverse Recovery Charge  Reverse Recovery Time  Softness Factor (t <sub>b</sub> /t <sub>a</sub> )		V <sub>R</sub> = 390 V,		_	4.3	-	Α		
Q <sub>rr</sub>			— T <sub>C</sub> = 125°C		/	110	-	nC		
dI <sub>M</sub> /dt	Maxim	um di/dt during	j t <sub>b</sub>			-	500	-	A/µs	
hermal	Chara	acteristics								
	Thermal Resistance Junction to Case					I .	I _ I	2.6	°C/W	
$R_{\theta JC}$	mem	ai Kesisiance	Junction to Case					2.0	O/ V V	





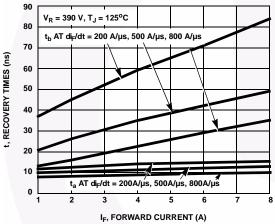


Figure 3. t<sub>a</sub> and t<sub>b</sub> Curves vs Forward Current

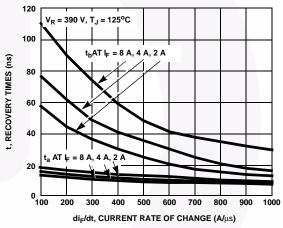


Figure 4. ta and tb Curves vs dif/dt

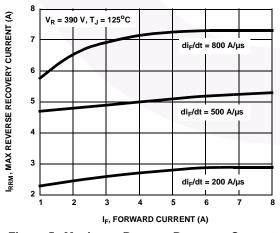


Figure 5. Maximum Reverse Recovery Current vs Forward Current

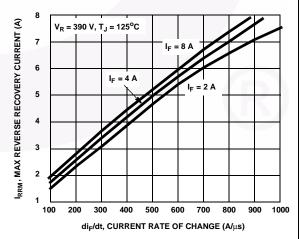
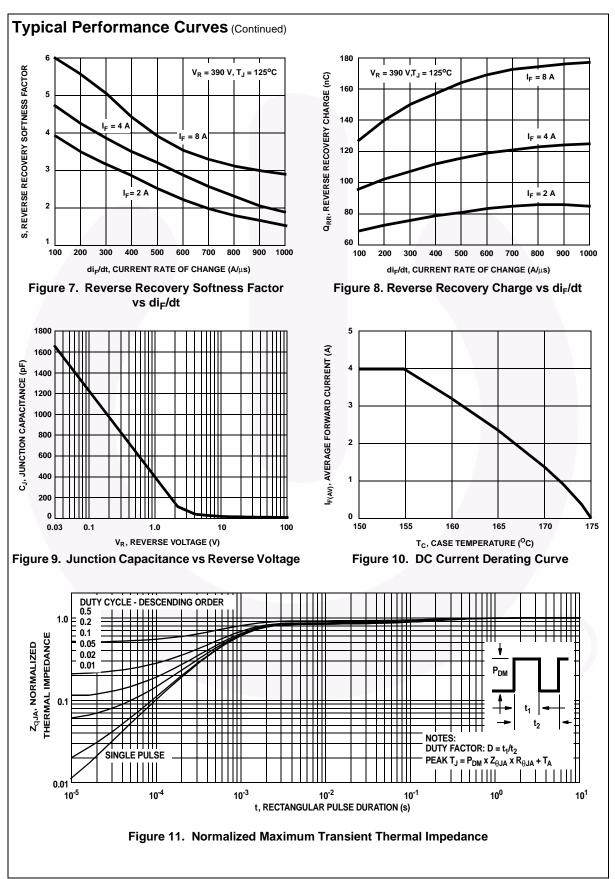
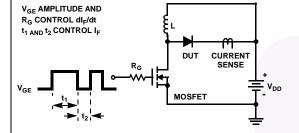


Figure 6. Maximum Reverse Recovery Current vs di<sub>F</sub>/dt



# Test Circuit and Waveforms



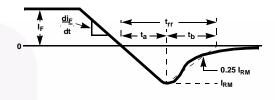


Figure 12. t<sub>rr</sub> Test Circuit

Figure 13.  $t_{rr}$  Waveforms and Definitions

```
I = 0.5A
L = 80mH
R < 0.1Ω
V<sub>DD</sub> = 200V
E<sub>AVL</sub> = 1/2LI<sup>2</sup> [V<sub>R(AVL)</sub>/(V<sub>R(AVL)</sub> - V<sub>DD</sub>)]
Q<sub>1</sub> = IGBT (BV<sub>CES</sub> > DUT V<sub>R(AVL)</sub>)

CURRENT
SENSE
V<sub>DD</sub>
V<sub>DD</sub>
UT
DUT
- •
```

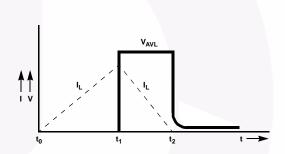


Figure 14. Avalanche Energy Test Circuit

Figure 15. Avalanche Current and Voltage Waveforms

# **Mechanical Dimensions**

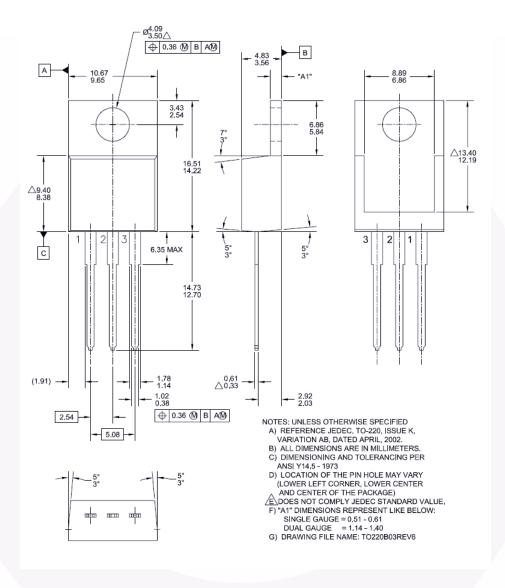


Figure 16. TO-220 3L - TO-220, MOLDED, 3LEAD, JEDEC VARIATION AB

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105318, г. Москва, ул. Щербаковская д. 3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

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